

(54) CHIP COMPONENT MOUNTING STRUCTURE

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(71) FUJITSU GENERAL LTD (72) NOBUTOMO MATSUMURA

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PURPOSE: To enable a flip chip component where fine connection pads are formed on its one side to be easily mounted on the surface of a board at an accurate position and surely connected by fusion.

CONSTITUTION: A first green sheet 1 where connection lands 6 and a conductor pattern 7 are formed and a second green sheet 8 where through-holes 9 are bored corresponding to the connection lands 6 are made to overlap each other for the formation of a multilayered board 10, solder paste 12 is filled into the through-holes 9, a bump 11 is formed on the pad 3 of a mounted flip chip component 2, the tip of the bump 11 is placed making the through-hole 9 serve as a guide, and then the flip chip component 2 is connected by reflowing.

